



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-09-29
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Laurent TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F100VBT6B	Y01L*420XXXZ	A	9994	2014-03-07
Amount		UoM	Unit type	ST ECOPACK Grade
681.44		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAuAg	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	100	L bend	
Comment	Package: LQFP 100L 14x14x1.4			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	Y01L*420XXXZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	6.469	mg	supplier	die	Silicon (Si)	7440-21-3		6.198	mg	958108	9095
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	3710	35
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.024	mg	3710	35
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.049	mg	7575	72
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.010	mg	1546	15
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.015	mg	2319	22
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.149	mg	23033	219
Die Attach	Other inorganic materials	3.240	mg	supplier	Glue	Acrylic resins	Trade secret		0.486	mg	150000	713
Die Attach				supplier	Glue	Resin	Trade secret		0.081	mg	25000	119
Die Attach				supplier	Glue	Silver (Ag)	7440-22-4		2.592	mg	800000	3804
Die Attach				supplier	Glue	Treated silica	96-48-0		0.081	mg	25000	119
Leadframe	Other inorganic materials	144.731	mg	supplier	Alloy	Copper (Cu)	7440-50-8		136.684	mg	944400	200581
Leadframe				supplier	Alloy	Iron (Fe)	7439-89-6		3.294	mg	22759	4834
Leadframe				supplier	Alloy	Phosphorous (P)	7723-14-0		0.042	mg	290	62
Leadframe				supplier	Alloy	Zinc (Zn)	7440-66-6		0.168	mg	1161	247
Leadframe				supplier	Coating	Nickel (Ni)	7440-02-0		4.431	mg	30615	6502
Leadframe				supplier	Coating	Palladium (Pd)	7440-05-3		0.094	mg	649	138
Leadframe				supplier	Coating	Gold(Au)	7440-57-5		0.009	mg	62	13
Leadframe				supplier	Coating	Silver(Ag)	7440-22-4		0.009	mg	62	13
Encapsulation	Other inorganic materials	524.971	mg	supplier	Molding compound	Epoxy Resin (Proprietary)	Proprietary		15.388	mg	29312	22582
Encapsulation				supplier	Molding compound	Phenol Resin (Proprietary)	Proprietary		15.388	mg	29312	22582
Encapsulation				supplier	Molding compound	Fused Silica (SiO2)	60676-86-0		465.983	mg	887636	683821
Encapsulation				supplier	Molding compound	Carbon Black	1333-86-4		2.565	mg	4886	3764
Encapsulation				supplier	Molding compound	Metal Hydroxide	Proprietary		25.647	mg	48854	37636
Wire	Other inorganic materials	1.534	mg	supplier	Wire	Gold (Au)	7440-57-5		1.519	mg	990222	2229
Wire				supplier	Wire	Palladium (Pd)	7440-05-3		0.015	mg	9778	22
Finishing	Other inorganic materials	0.495	mg	supplier	Connection coating	Nickel (Ni)	7440-02-0		0.437	mg	882828	641
Finishing				supplier	Connection coating	Palladium (Pd)	7440-05-3		0.026	mg	52525	38
Finishing				supplier	Connection coating	Gold(Au)	7440-57-5		0.016	mg	32323	23
Finishing				supplier	Connection coating	Silver(Ag)	7440-22-4		0.016	mg	32323	23